

光鎔科技股份有限公司
Epileds Technologies, Inc.
Product specification of 42 x42 mil red LED chip

1. Scope:

This specification applies to AlInGaP metal bonding 42 x 42mil red LED chip, BN-R4242G-A3 ◦

2. Materials :

2.1 P-pad : Au alloy ◦

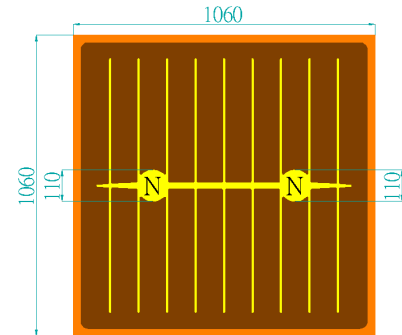
2.2 N-pad : Au alloy ◦

3. Dimensions :

3.1 Chip size : 1060±25μm x 1060±25μm ◦

3.2 N-pad : φ110±10μm, thickness 3.5±0.3μm ◦

3.3 Chip thickness : 200μm±25μm ◦



4. Electro-optical characteristics and specification: (Tc=25°C)

4.1 Electro-optical characteristics

Test parameter	Condition	Min	Typ	Max	Unit
Dominant wavelength(Wd)	350mA	600	-	650	nm
Luminous intensity(Iv)	350mA	1600	-	15700	mcd
Forward voltage(Vf4)	10uA	1.3	-	2.5	V
Forward voltage(Vf1)	350mA	1.8	-	2.8	V
Reverse current (Ir)	-10V	0	-	2	uA

4.2 Electro-optical specification(Bin table) :

Wd		Iv				Vf1 (V)	Vf4 (V)	Ir (uA)	Vz (V)
Bin	nm	Bin	mcd	Bin	mcd				
RA	600~605	69	1600~1750	83	5400~5900	1.8~2.8	1.3~2.5	0~2	25~
RC	605~610	70	1750~1900	84	5900~6400				
RE	610~615	71	1900~2100	85	6400~7000				
RG	615~620	72	2100~2300	86	7000~7600				
RI	620~625	73	2300~2500	87	7600~8300				
RK	625~630	74	2500~2700	88	8300~9100				
RM	630~635	75	2700~2950	89	9100~10000				
RO	635~640	78	3500~3800	90	10000~10900				
RQ	640~645	79	3800~4150	91	10900~12000				
RS	645~650	80	4150~4500	92	12000~13100				
		81	4500~5000	93	13100~14400				
		82	5000~5400	94	14400~15700				

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* The detail technical and reliability datasheet are also available for your reference, please be free to contact us.

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